



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D

** : Required Field*

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2015-10-13
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Flavio Di Francesco	Representative Title	AMS MD CHAMPION
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement


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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	LDK7*1874AR6	A	BO2A	2015-10-13
	Amount	UoM	Unit type	ST ECOPACK Grade
	130.00	mg	Each	ECOPACK® 3

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
DSO	8.6x3.9x1.52	14	gull wing	
Comment	Package: K7 SO 14 .15 TO JEDEC MS-012; MD valid for TS1874AIDT - TSV324IDT			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	true
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Exemption Id.	Description

QueryList : REACH-15th June 2015				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	LDK7*1874AR6					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	2.981	mg	supplier	die	Silicon (Si)	7440-21-3		2.951	mg	989936	22700
				supplier	metallization	Aluminium (Al)	7429-90-5		0.010	mg	3355	77
				supplier	Passivation	Silicon Nitride	12033-89-5		0.008	mg	2684	62
				supplier	Passivation	Silicon Oxide	7631-86-9		0.006	mg	2013	46
				supplier	glass coating	Glass: Silicon Dioxide	7631-86-9		0.006	mg	2013	46
Leadframe	Copper & its alloys	36.414	mg	supplier	alloy	Copper (Cu)	7440-50-8		33.885	mg	930549	260654
				supplier	alloy	Iron (Fe)	7439-89-6		0.797	mg	21887	6131
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.048	mg	1318	369
				supplier	alloy	Zinc (Zn)	7440-66-6		0.042	mg	1153	323
				supplier	metallization	Silver (Ag)	7440-22-4		1.642	mg	45093	12631
Die attach	Other inorganic materials	1.069	mg	supplier	glue	Silver (Ag)	7440-22-4		0.971	mg	908326	7469
				supplier	glue	acrylate	Proprietary		0.053	mg	49579	408
				supplier	glue	Methacrylate	Proprietary		0.043	mg	40225	331
				supplier	glue	acrylate	Proprietary		0.001	mg	935	8
				SVHC	glue	NMP	872-50-4		0.001	mg	935	8
Bonding wires	Other inorganic materials	0.082	mg	supplier	wire	Copper (Cu)	7440-50-8		0.082	mg	1000000	631
Encapsulation	Other Organic Materials	89.454	mg	supplier	mold compound	Silica, vitreous	60676-86-0		78.451	mg	876998	603469
				supplier	mold compound	Epoxy resin	85954-11-6		3.578	mg	39998	27523
				supplier	mold compound	Epoxy	29690-82-2		3.578	mg	39998	27523
				supplier	mold compound	phenol resin	Proprietary		2.684	mg	30004	20646
				supplier	mold compound	additive	Proprietary		0.895	mg	10005	6885
				supplier	mold compound	carbon black	1333-86-4		0.268	mg	2996	2062